

34. The method of claim **33** wherein the flexible donor substrate is coated with a release layer.

35. The method of claim **33** further comprising detaching the conductive layer from the flexible donor substrate and applying the conductive layer to a substrate of choice.

36. The method of claim **35** wherein the conductive layer is patterned prior to being detached from the flexible donor substrate.

37. The method of claim **35** wherein the substrate of choice comprises at least one heated region and at least one unheated region, wherein the conductive layer bonds the heated region more firmly than it bonds with the unheated region.

38. The method of claim **37** further comprising removing only the conductive layer in the unheated region.

39. The method of claim **35** wherein the conductive layer is applied to the substrate of choice by applying pressure to the conductive layer according to a pattern, and wherein the conductive layer bonds more firmly with a pressured region than it with an unpressured region.

40. The method of claim **39** further comprising removing only the conductive layer on the unpressured region.

41. The method of claim **35** wherein the substrate of choice is rigid.

42. The method of claim **35** wherein the substrate of choice is flexible.

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